



Product/Process Change Notice - PCN 11_0047 Rev. B

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Re-design and Wafer Fabrication transfer of the ADG508F/ADG509F

Publication Date: 28-Oct-2011

Effectivity Date: 28-Oct-2011 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Improved Signal range and Idd specification specifications on redesigned die

Description Of Change

All Layer Re-design and transfer of the ADG508F/ADG509F from the 4" High Voltage Switch Dielectrically Isolated SOI wafer fabrication process in Analog Devices, Limerick, Ireland to the equivalent 8" wafer fab process at the same location.

Data sheet specifications will change as per the attached evaluation report.

Rev. B: As per attached updated evaluation report for the 8" product the Signal range specification for 25C has been updated from Vss +1.5 & Vdd -1.5 advised on previous revs of this PCN to Vss +1.4 & Vdd -1.4 and Idd specification for 25C has been updated from 0.1 to 0.05.

These changes are reflected in Rev. F of the ADG508F/ADG509F data sheet.

Reason For Change

Increased wafer fabrication capacity.

Rev B: Redesign and transfer resulted in better than anticipated specifications.

Impact of the change (positive or negative) on fit, form, function & reliability

This transfer will not affect the form, fit, function, quality or reliability of the ADG508F/ADG509F.

Product Identification *(this section will describe how to identify the changed material)*

This PCN will be updated prior to the effectivity date with the date code of changeover to new materials for all models of the ADG508F and ADG509F. Rev A Update: Datecode for changeover of ADG508F/ADG509F models is DC 1123 and onwards.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

Supporting Documents

Attachment 1: Type: Qualification Report Summary

ADI_PCN_11_0047_Rev_B_ADG508F_ADG509F_Qual Summary.pdf

Attachment 2: Type: Datasheet Specification Comparison

ADI_PCN_11_0047_Rev_B_ADG508F_ADG509F_Transfer_Comparison Updated 201011.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (23)

ADG508F / ADG508FBN	ADG508F / ADG508FBNZ	ADG508F / ADG508FBRN	ADG508F / ADG508FBRN-REEL7	ADG508F / ADG508FBRNZ
ADG508F / ADG508FBRNZ-REEL7	ADG508F / ADG508FBRJZ	ADG508F / ADG508FBRUZ-REEL7	ADG508F / ADG508FBRW	ADG508F / ADG508FBRWZ
ADG508F / ADG508FBRWZ-REEL	ADG509F / ADG509FBN	ADG509F / ADG509FBNZ	ADG509F / ADG509FBRN	ADG509F / ADG509FBRN-REEL7
ADG509F / ADG509FBRNZ	ADG509F / ADG509FBRNZ-REEL7	ADG509F / ADG509FBRUZ	ADG509F / ADG509FBRUZ-REEL7	ADG509F / ADG509FBRW
ADG509F / ADG509FBRW-REEL	ADG509F / ADG509FBRWZ	ADG509F / ADG509FBRWZ-REEL		

Appendix B - Revision History

Rev	Publish Date	Rev Description
Rev. -	07-Mar-2011	Initial Release
Rev. A	12-Jul-2011	Updated with datecode changeover
Rev. B	28-Oct-2011	Improved Signal range and Idd specification specifications on redesigned die

Analog Devices, Inc.

DocId:1743 Parent DocId:None Layout Rev:6